

PATENT ABSTRACTS OF JAPAN

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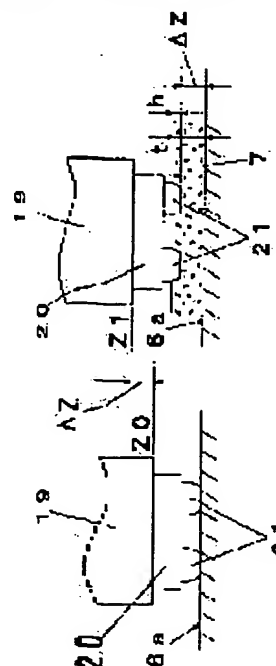
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(54) DEVICE AND METHOD FOR MOUNTING ELECTRONIC PART WITH BUMP

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a device and a method for mounting an electronic part with bumps which can easily adjust the quantity of conductive paste applied thereon.

SOLUTION: In a method of mounting an electronic part with bumps which mounts an electronic part with a bumps on a board with a conductive paste, flattening is performed by lowering a suction head 19 which holds an electronic part 20 with a bumps and pressing the bumps 21 against a flat bottom face 6a, and the level position Z0 of the suction head 19 at this time is stored. Then, the transfer level position which shows the level position Z1 at the time of transfer of the conductive paste is obtained, based on this level position Z0 and a level offset value ΔZ inputted in advance, and the conductive paste is transferred to the bump by raising the suction head 19 again after lowering it to the transfer level position Z1 as against the paint film of the conductive paste 7. As a result, the quantity of the applied conductive paste can be adjusted merely by changing the level offset value ΔZ .



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